

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
1	PROPOSE ONLY	ALLEN	2012.10.08

(NOTE)

MATERIAL:

Insulator: High Temperature Thermoplastic, 94V-0.
 Contact: Copper Alloy
 Shell: STAINLESS

PLATING:

Contact: Plated 30u" Ni Overall Contact G/F
 Shell: Plated 30u" Ni Overall
 Plated G/F Selective Contact Area

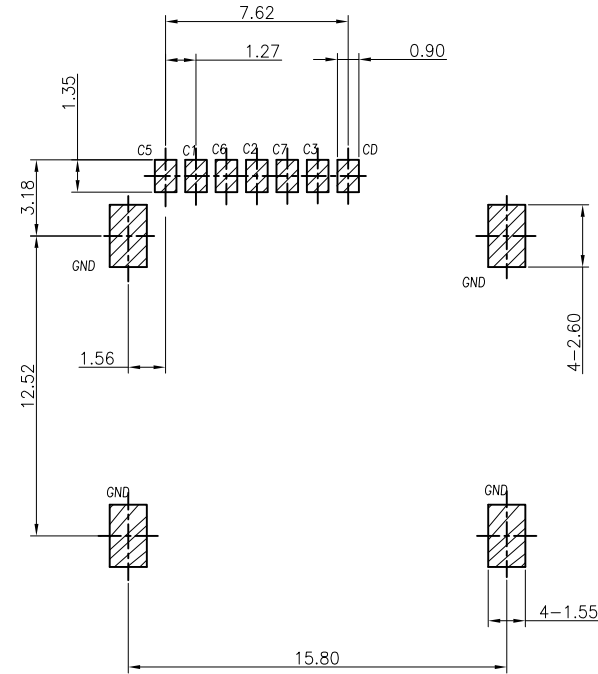
Electrical:

Current Rating :0.5mA max.
 Voltage Rating :50V DC MAX
 Ambient Temperature Range :-20°C~+85°C
 Storage Temperature Range :-40°C~+70°C
 Ambient Humidity Range :95% R.H. Max.
 Contact Resistance:100mΩ max.
 Insulation Resistance:1000MΩ min./250V DC
 Dielectric Withstanding Voltage:500V AC
 Mating Cycles:5,000 Insertions
 Temperature: 260°C ±5'

6. PART No.:

MS 0 PP - 13 00 06- 03 G T

MicroSIM CON-
 0=WITHOUT POST
 PP=PUSH Type.
 13:HEIGHT 1.35mm
 T=With Detect
 G=gold plating
 14=Product Order
 Pin NO. 6=6Pin
 00=NORMAL TYPE.(ON PCB)

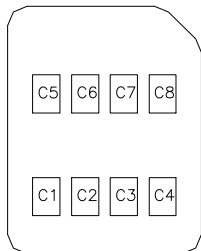


■ CIRCUT TRACE KEEP OUT AREA
 ▨ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES
 IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

【 SIM CARD PAD LAYOUT 】



【 SIM Card Pin Assignments 】

PIN	Name
C1	Vcc
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	Vpp
C7	I/O
C8	Reserved

UNLESS OTHERWISE SPECIFIED TOLERANCES		 深圳市顺宏康科技有限公司			
DECIMALS:	ANGLES:	TITLE	1.35mm (Detect) Push Micro SD CARD CONN.		
X :±0.5	X :±2°	DWN	ALLEN	PART NO.	SHK-10362
X.X :±0.20	X.X :±1°	CHKD	KEVIN	SCALE:1:1	UNIT: mm
X.XX :±0.10		APVD	ERIC.W	SIZE: A3	SHEET:2 OF 2
					REV: A2
CUSTOMER COPY					